S2   3 ("6148900").PN.   USPAT;   EPO; JPO; DERWENT;   IBM_TDB   USPAT; USOCR; EPO; JPO; DERWENT;   IBM_TDB   USPAT;   EPO; JPO							
S2   3 ("6148900").PN.   US-PGPUB; DOR US-PGPUB; US-PG	ı	Hits	Search Query	DBs		Plurals	Time Stamp
S3 6 (("5859407") or ("6080936") or ("6115913")).PN.  S4 3 @ad<="20040318" and 'interposer' with 'alumina' and 'IC' with 'silicon' EPO; JPO; DERWENT; IBM_TDB  S5 11 @ad<="20040318" and 'interposer' with 'alumina' and 'IC' with 'silicon' EPO; JPO; DERWENT; IBM_TDB  S6 14 @ad<="20040318" and 'interposer' with 'alumina' and 'IC' with 'silicon' EPO; JPO; DERWENT; IBM_TDB  S6 14 @ad<="20040318" and 'interposer' with 'alumina' and 'IC' bip' EPO; JPO; DERWENT; IBM_TDB  S7 240 @ad<="20040318" and 'interposer' same 'alumina' and 'IC chip' US-PGPUB;	S1	2	"20040173891"	USPAT; EPO; JPO; DERWENT;	OR	ON	2005/07/21 12:13
Company   Comp	S2	3	("6148900").PN.	USPAT; USOCR; EPO; JPO; DERWENT;	OR	OFF	2005/07/21 12:14
With 'alumina' and 'IC' with 'silicon'   USPAT;   EPO; JPO;   DERWENT;   IBM_TDB   USPAT;   EPO; JPO;   DERWENT;   IBM_TDB   USPAT;   EPO; JPO;   DERWENT;   E	S3	6		USPAT; USOCR; EPO; JPO; DERWENT;	OR	OFF	2005/07/21 12:18
With 'alumina' and 'IC'	S4	3		USPAT; EPO; JPO; DERWENT;	OR	ON	2005/07/22 09:22
Same 'alumina' and 'IC chip'   USPAT;   EPO; JPO;   DERWENT;   IBM_TDB   OR   ON   2005/07/21 12:44   USPAT;   EPO; JPO;   DERWENT;   EPO; JPO;   DERWENT;   EPO; JPO;   DERWENT;   IBM_TDB   OR   ON   2005/07/21 12:45   OR   ON   2005/07/21 12:45   OR   OR   ON   2005/07/21 12:45   OR   OR   ON   ON   ON   ON   ON   ON	S5	11		USPAT; EPO; JPO; DERWENT;	OR	ON	2005/07/21 12:25
same 'alumina' and 'IC chip'  USPAT; EPO; JPO; DERWENT; IBM_TDB  S8 123 @ad<="20040318" and 'board' with US-PGPUB; OR ON 2005/07/21 12:45	S6	14		USPAT; EPO; JPO; DERWENT;	OR	ON	2005/07/21 12:50
'alumina' and 'IC chip' USPAT;	<b>S</b> 7	240		USPAT; EPO; JPO; DERWENT;	OR	ON	2005/07/21 12:44
EPO; JPO; DERWENT; IBM_TDB	S8	123	1 🔾 1	USPAT; EPO; JPO; DERWENT;	OR	ON	2005/07/21 12:45
S9 2 @ad<="20040318" and 'board' with 'alumina' and 'interposer' and 'IC chip'  US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	S9	2	'alumina' and 'interposer' and 'IC	USPAT; EPO; JPO; DERWENT;	OR	ON	2005/07/21 12:45
S10	S10	67		USPAT; EPO; JPO; DERWENT;	OR	ON	2005/12/14 08:43
S11 1 "20020041489".PN. US-PGPUB OR ON 2005/07/21 12:52	S11	1	"20020041489".PN.	US-PGPUB	OR	ON	2005/07/21 12:52

S12	1	"6479760".PN.	USPAT; USOCR	OR	ON	2005/07/21 12:52
S14	7568	@ad<="20040318" and (174/260). ccls. or (174/262).ccls. or (361/760).ccls. or (361/803).ccls. (257/698).ccls. or (257/738).ccls. or (257/778).ccls. and 'alumina'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 14:03
S17	9082	@ad<="20040318" and (174/260). ccls. or (174/262).ccls. or (361/760).ccls. or (361/803).ccls. or (257/698).ccls. or (257/738).ccls. or (257/778).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 12:59
S18	7568	@ad<="20040318" and (174/260). ccls. or (174/262).ccls. or (361/760).ccls. or (361/803).ccls. or (257/698).ccls. or (257/738).ccls. or (257/778).ccls. and 'alumina'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 12:56
S19	7408	@ad<="20040318" and (174/260). ccls. or (174/262).ccls. or (361/760).ccls. or (361/803).ccls. or (257/698).ccls. or (257/778).ccls. and 'alumina' near 'interposer' and 'IC chip' near 'silicon'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 13:00
S20	3	@ad<="20040318" and 'alumina' with 'interposer' and 'IC chip' with 'silicon'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 12:57
S22	1	"6085260".PN.	USPAT; USOCR	OR	ON	2005/07/21 13:02
S23	1	@ad<="20040318" and 'interposer' and 'IC chip' with 'silicon' same 'thermal expansion coefficient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 13:21
S24	150	@ad<="20040318" and 'IC' same 'silicon' same 'thermal expansion coefficient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 13:21
S25	76	@ad<="20040318" and 'IC' with 'silicon' with 'thermal expansion coefficient'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 13:25
S26	162	@ad<="20040318" and 'thermal expansion coefficient' with 'silicon' with 'ppm'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 13:29
S27	18	@ad<="20040318" and 'thermal expansion coefficient' with 'silicon' with 'ppm' and 'interposer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 13:40

S28	10	@ad<="20040318" and 'silicon' with 'ppm' and 'interposer' same 'inorganic'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 13:40
S29	1562	@ad<="20040318" and (257/700). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 14:04
S30	1318	@ad<="20040318" and (29/852). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 14:04
S31	1229	@ad<="20040318" and (257/734). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 14:05
S32	4	(("6388198") or ("6222276")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/21 14:31
S33	14	@ad<="20040318" and 'interposer' with 'silicon nitride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 15:36
S34	2	("6507497").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/21 15:31
S35	28	@ad<="20040318" and 'interposer' same 'silicon nitride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 16:10
S37	601	@ad<="20040318" and 'board' with 'silicon' with 'silicon nitride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 16:11
S38	0	@ad<="20040318" and 'board' with 'silicon' with 'silicon nitride' same 'interposer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 16:12
S39	7	@ad<="20040318" and 'board' same 'silicon' same 'silicon nitride' same 'interposer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 16:12

S40	18	@ad<="20040318" and 'IC' with 'silicon' same '10 mm'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 09:26
S41	4	@ad<="20040318" and 'IC chip' with 'silicon' same '10 mm'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 09:23
S42	423	@ad<="20040318" and 'IC' same '10 mm'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 09:27
S43	130	@ad<="20040318" and 'semiconductor chip' same '10 mm'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 09:27
S44	61	@ad<="20040318" and 'interposer' and 'alumina' and ('coefficient of thermal expansion' or 'CTE')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/14 08:43